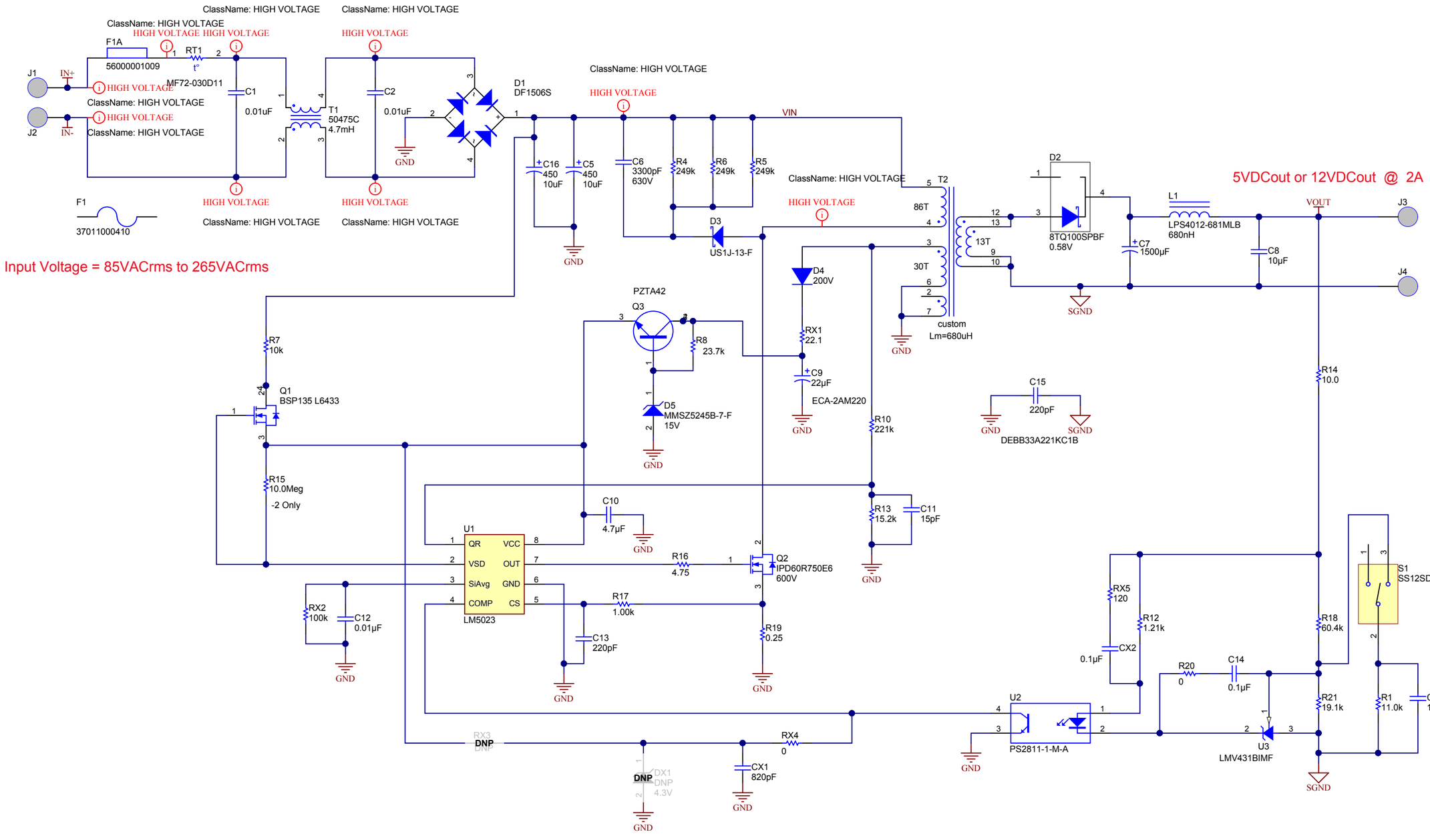
Note: PMP7991 is build on PMP7883 PC board



Designed for: Public Release		Mod. Date: 9/29/2015	
Project Title: Offline Isolated Flyback 5V or 12V DCout @ 2A			
Number: PMP7991	Rev: 1	Sheet Title: PMP7991	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 1 of 2
Drawn By: Not shown in title block		File: PMP7991 Schematics.SchDoc	Size: B
Engineer: Bob Sheehan/Hrag Kasparian		Contact: http://www.ti.com/support	

TEXAS INSTRUMENTS
http://www.ti.com

FID1

PCB: PMP7883 RevC

PMP7883 RevC

PCB
LOGO
Texas Instruments

FID2

FID3

LBL1

PCB Label

Size: 0.65" x 0.20 "

ZZ1

Label Assembly Note

This Assembly Note is for PCB labels only

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

Number: PMP7991	Rev: 1	Designed for: Public Release	Mod. Date: 9/21/2015
SVN Rev: Version control disabled		Project Title: Offline Isolated Flyback 5V or 12V DCout @ 2A	
Drawn By:		Sheet Title:	
Engineer: Bob Sheehan/Hrag Kasparian		Assembly Variant: 001	Sheet: 2 of 2
		File: PMP7991_Hardware_ANSI-B.SchDoc	Size: B
		Contact: http://www.ti.com/support	http://www.ti.com

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